Hewlett Packard Enterprise

**Product End-of-Life Disassembly Instructions**

| Product Category: Networking Equipment |
|---|
| **Marketing Name / Model [List multiple models if applicable.]** |
| HPE Altoline 6822 48XG 6QSFP28 x86 ONIE Switch (JL442A) |
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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|---|---|---|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm<br>Main and CPU board | 2 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 0 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 0 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 0 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 0 |
| External electrical cables and cords | Power cords | 2 |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | 0 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos | | 0 |
| Components, parts and materials containing refractory ceramic fibers | | 0 |



HPE instructions for this template are available at MF877-01

| Item Description | Notes | Quantity of items included in product |
|---|---|---|
| Components, parts and materials containing radioactive substances | | 0 |

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|---|---|
| Phillips screwdriver | M3, M2.5 |
| Flat-blade screwdriver | |
| Small adjustable wrench | |
| Needle nose pliers | |
| socket wrench | |

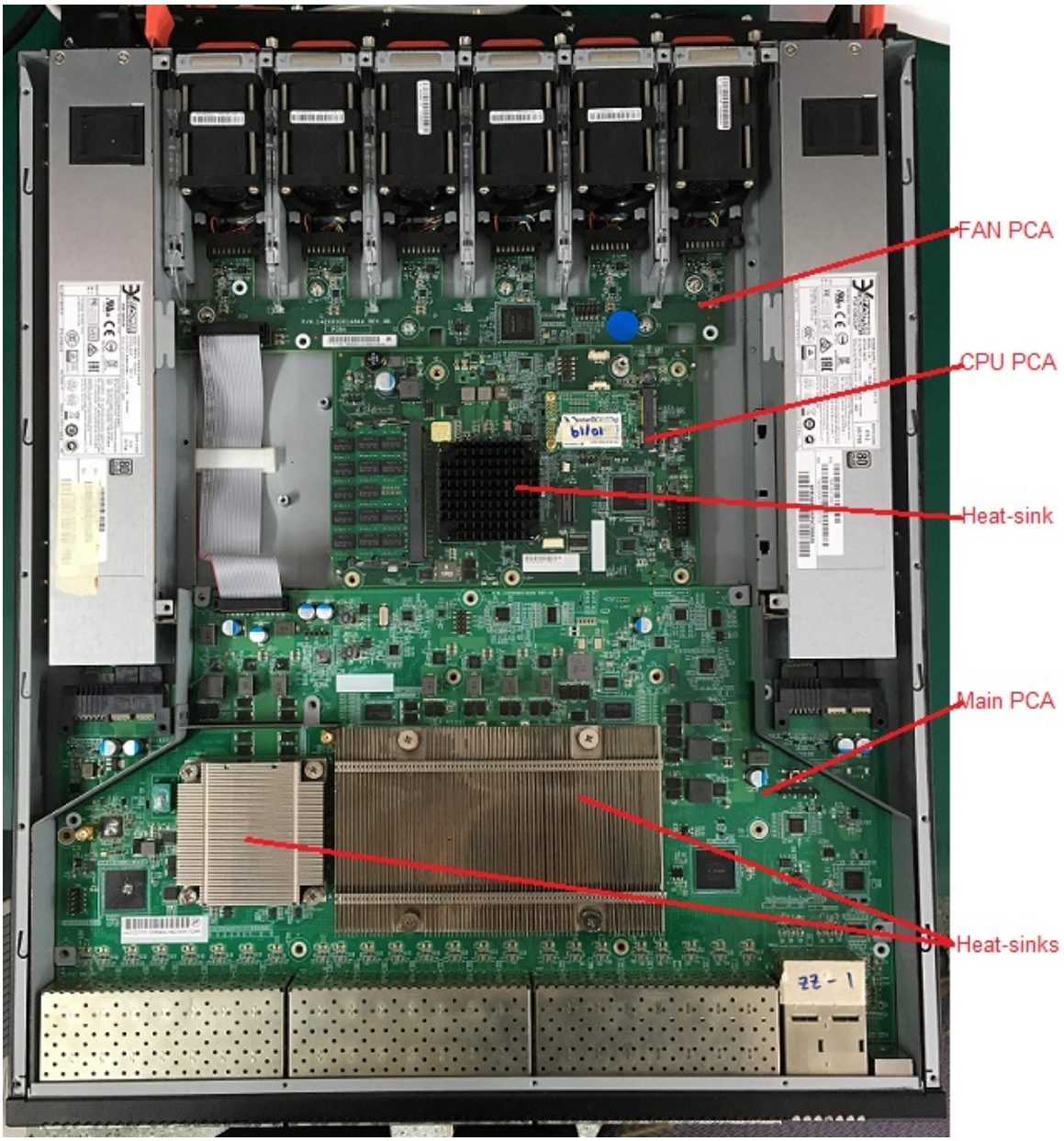
## 3.0 Product Disassembly Process

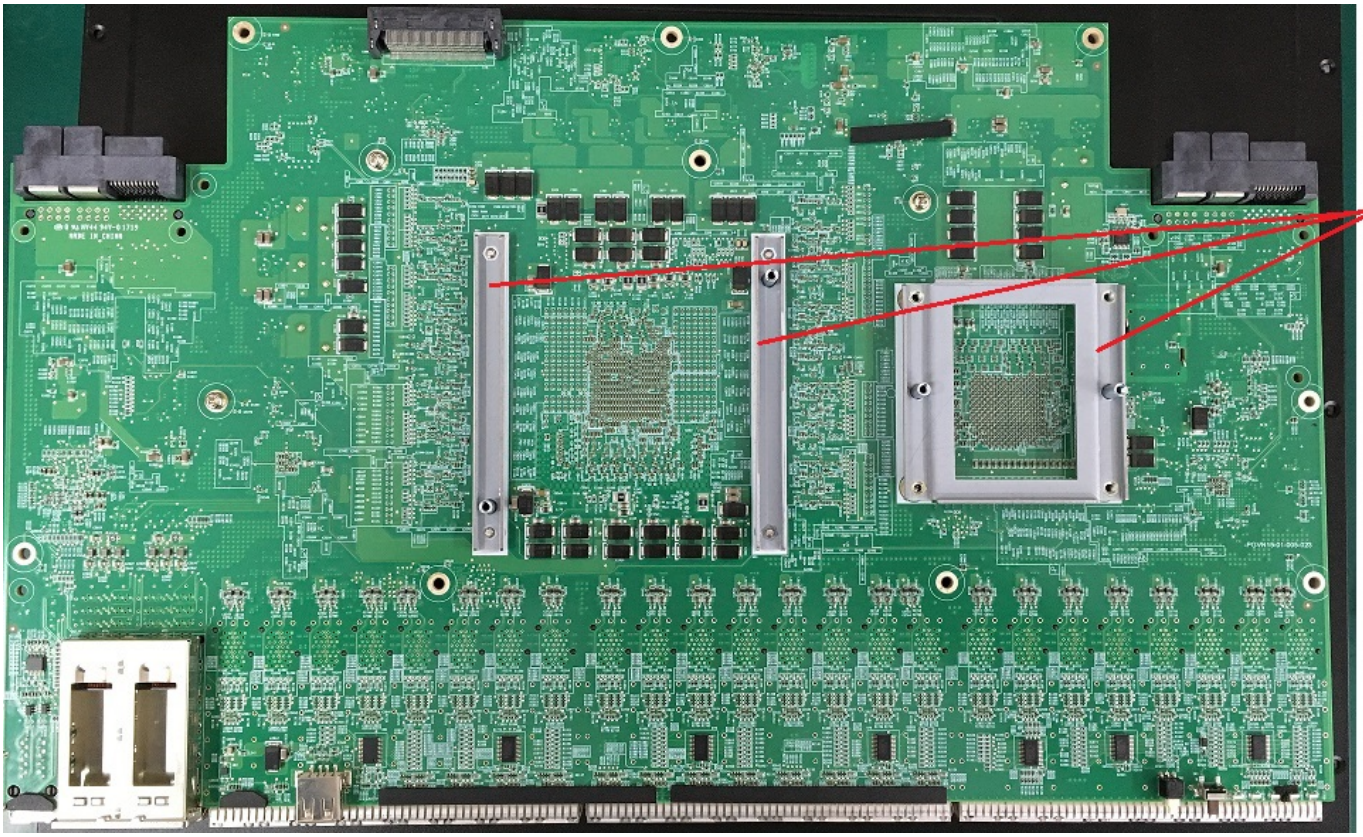
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

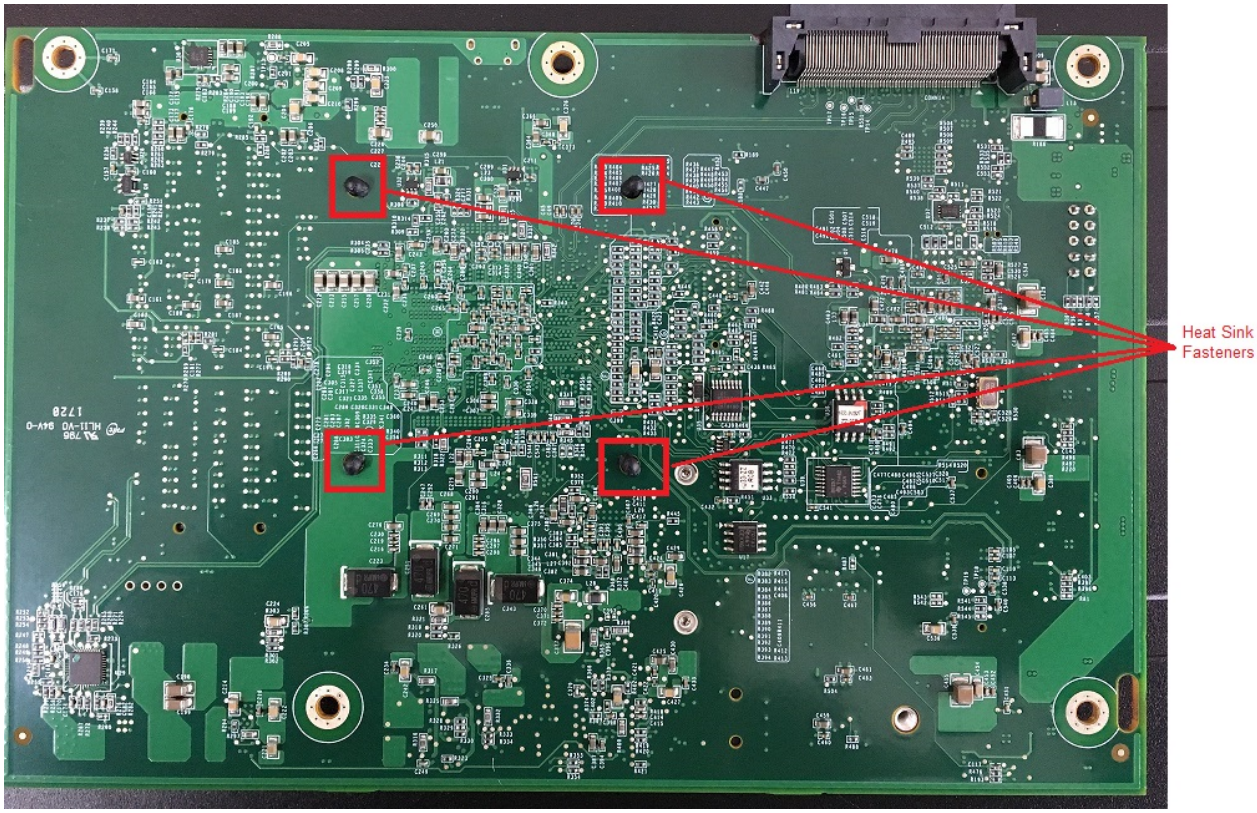
1. Remove the chassis lid
    1. Using a Phillips screwdriver, remove the screws (qty 25)
    2. Slide the lid off the chassis
    3. Slide the QSFP lid off the chassis bottom.
2. Remove the two power supplies
    1. Locate the power supplies on the right side as you are facing the back of the chassis
    2. While pressing the release lever toward the handle, pull the power supply out of the chassis
    3. Repeat for the other power supply
3. Remove the six Fan Module
    1. Locate the Fan Module on the right side as you are facing the back of the chassis
    2. Using a Phillips screwdriver to remove the screw, pull the Fan Module out of the chassis.
    3. Repeat for the other Fan Module
4. Remove the CPU PCA
    1. Using a Phillips screwdriver, remove the screw on the CPU PCA
    2. Slide the CUP PCA toward the back of the chassis then lift the right side to remove it
5. Remove the main PCA
    1. Disconnect the  fan cable from the main PCA
    2. Using a Phillips screwdriver, remove the 12 screws holding down the main PCA
    3. Using a socket wrench, remove the 4 spacer holding down the main PCA
    4. Using a Phillips screwdriver, remove the 2 screws on air baffles
    5. Remove the 2 air baffles.
    6. Slide the main PCA toward the back of the chassis then lift the rear side to remove it
    7. Using a Phillips screwdriver, loosen the four screws holding down the CPU heat sink
    8. Remove the 2 heat sinks and brackets
6. Remove the FAN PCA
    1. Using a Phillips screwdriver, remove the screw on the FAN PCA
    2. Lift the FAN PCA to remove it

7. Remove the remaining three heatsinks
    1. Flip the CPU PCA
    2. Use needle nose pliers to pinch the four heat sink fasteners while removing a heat sink from the CPU PCA
    3. Using a Phillips screwdriver, loosen the four screws holding down the main heat sink
    4. Remove the heat sink and bracket
    5. Repeat the above step for another heat sinks

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).





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